

AREA ARRAY PACKAGE WITH LOW INDUCTANCE CONNECTING DEVICE

Abstract

An area-array integrated circuit package assembly are provided with a plurality of electrically conductive connectors attached to the package I.O. pads, that are used to connect the package to a printed circuit card or other component. The connectors comprise at least two parallel conductors flexing together in the same direction, electrically insulated from each other for a portion of their length between the package and printed circuit card to provide for reduced interconnection inductance. The connection with the component contact pads can be achieved by mechanically pressing the package and circuit card together or with the use of bonding material.